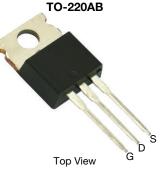
SUP60030E Vishay Siliconix

www.vishay.com

# N-Channel 80 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) MAX.	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (TYP.)			
80	0.0034 at $V_{GS}$ = 10 V	120	94			
80	0.0036 at $V_{GS}$ = 7.5 V	120	54			



#### **Ordering Information:**

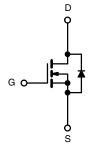
SUP60030E-GE3 (lead (Pb)-free and halogen-free)

#### FEATURES

- TrenchFET<sup>®</sup> power MOSFET
- Maximum 175 °C junction temperature
- Very low  $Q_{gd}$  reduces power loss from passing through  $V_{plateau}$
- 100 %  $R_{\rm q}$  and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### APPLICATIONS

- Power supply
  Secondary synchronous rectification
- DC/DC converter
- Power tools
- Motor drive switch
- DC/AC inverter
- Battery management



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (	$T_{\rm C}$ = 25 °C, unless othe	rwise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	80	v
Gate-Source Voltage		V <sub>GS</sub>	± 20	v
	T <sub>C</sub> = 25 °C		120 <sup>d</sup>	
Continuous Drain Current ( $T_J = 150 \ ^\circ C$ )	T <sub>C</sub> = 70 °C	I <sub>D</sub>	120 <sup>d</sup>	<u>^</u>
Pulsed Drain Current (t = 100 μs)		I <sub>DM</sub>	250	A
Avalanche Current		I <sub>AS</sub>	70	
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	245	mJ
Marian and Darris Diable at an 8	T <sub>C</sub> = 25 °C	D	375 <sup>b</sup>	w
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 125 °C		125 <sup>b</sup>	vv
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.4	0/11	

#### Notes

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).
- d. Package limited.

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**RoHS** COMPLIANT

HALOGEN

FREE



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static			•			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS}=0~V,~I_D=250~\mu A$	80	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2	-	4	- V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V	-	-	± 250	nA
		$V_{DS} = 80 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 80 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	150	
		$V_{DS}$ = 80 V, $V_{GS}$ = 0 V, $T_{J}$ = 175 °C	-	-	5	mA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V},  V_{GS} = 10 \text{ V}$	120	-	-	А
Drain Courses On State Desistance 8	Р	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	0.0028	0.0034	0
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 7.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	0.0030	0.0036	Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 30 \text{ A}$	-	82	-	S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>		-	7910	-	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V, V_{DS} = 40 V, f = 1 MHz$	-	3250	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	348	-	
Total Gate Charge <sup>c</sup>	Qg		-	94	141	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 40 V, $V_{GS}$ = 10 V, $I_{D}$ = 20 A	-	31	-	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		-	10	-	
Gate Resistance	Rg	f = 1 MHz	0.28	1.4	2.8	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	24	40	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 40 V, $R_L$ = 4 $\Omega$	-	24	40	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10$ Å, $V_{GEN} = 10$ V, $R_g = 1$ $\Omega$	-	34	60	ns
Fall Time <sup>c</sup>	t <sub>f</sub>		-	14	28	
Drain-Source Body Diode Ratings an	nd Characteris	stics <sup>b</sup> (T <sub>C</sub> = 25 °C)				
Pulsed Current (t = 100 µs)	I <sub>SM</sub>		-	-	250	А
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	$I_F = 10 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.8	1.5	V
Reverse Recovery Time	t <sub>rr</sub>		-	126	190	ns
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	I <sub>F</sub> = 34 A, di/dt = 100 A/μs	-	5	10	Α
Reverse Recovery Charge	Q <sub>rr</sub>		-	0.315	0.475	μC

Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

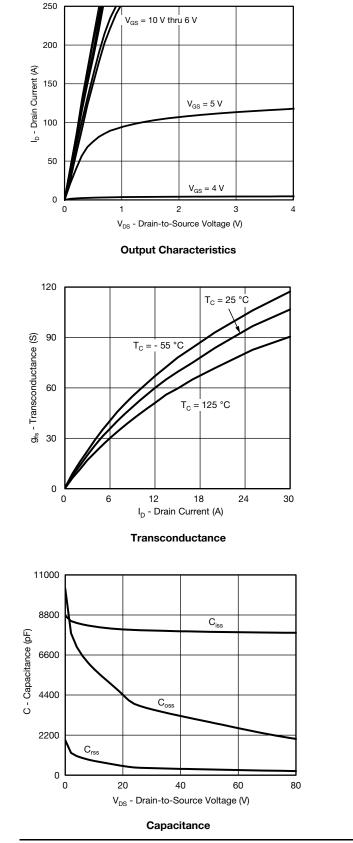
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

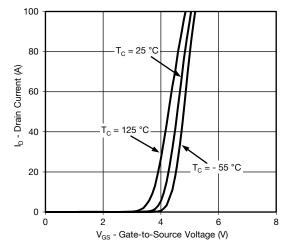
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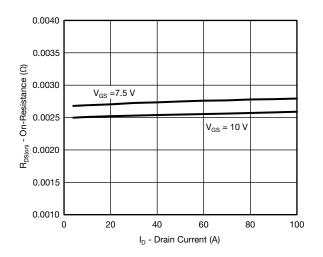
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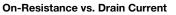
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)

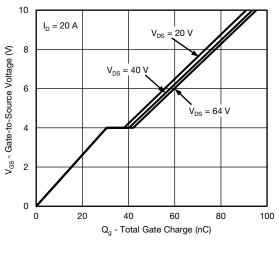




**Transfer Characteristics** 







Gate Charge

S15-1869-Rev. A, 10-Aug-15

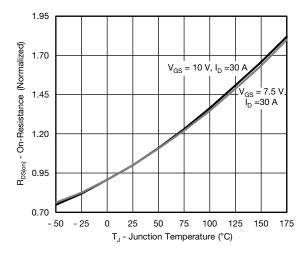
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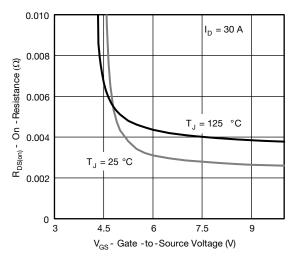


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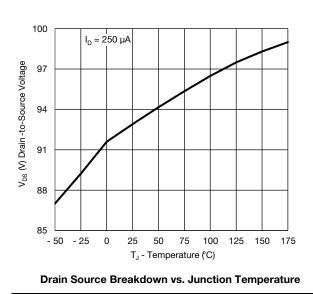
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**On-Resistance vs. Junction Temperature** 

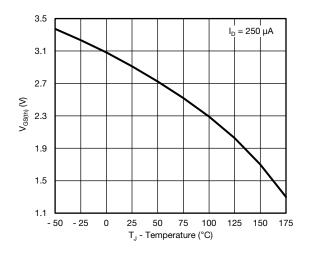


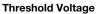
On-Resistance vs. Gate-to-Source Voltage

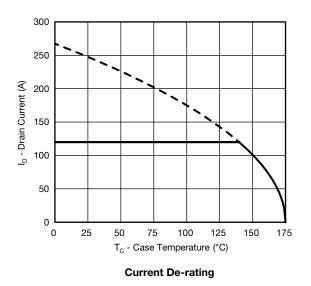


(Y) true for the second seco

Source Drain Diode Forward Voltage







S15-1869-Rev. A, 10-Aug-15

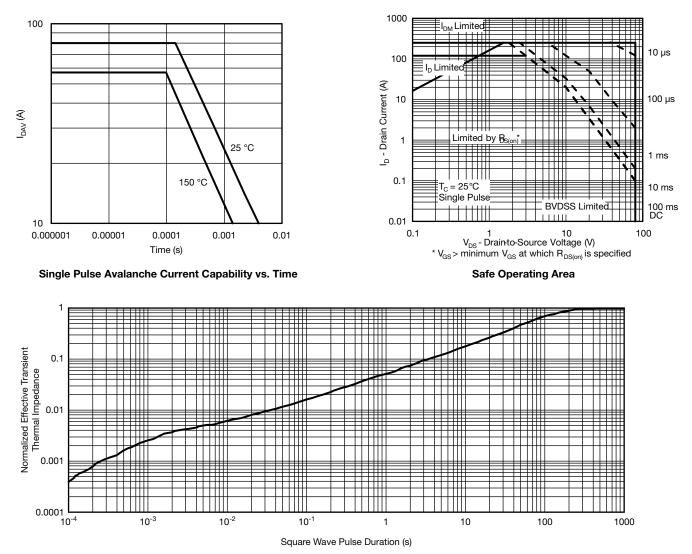
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### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)

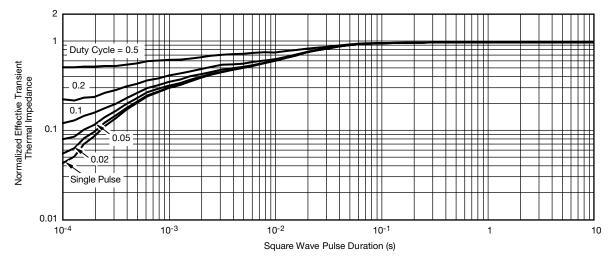


Normalized Thermal Transient Impedance, Junction-to-Ambient



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### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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# **TO-220AB**



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
	0413-Rev. P,		0.102	0.118

Note

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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